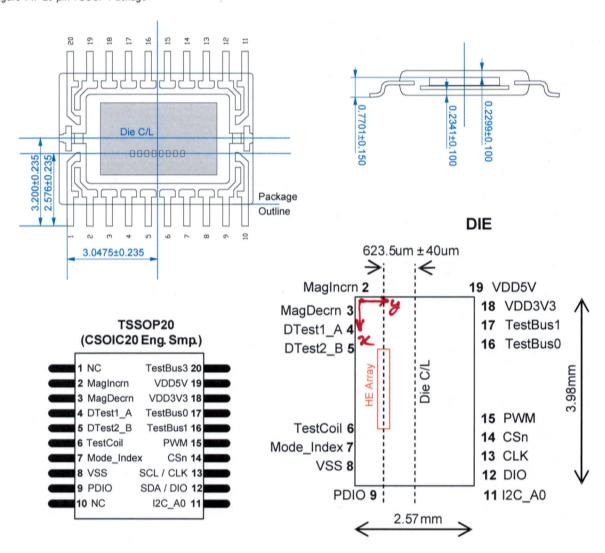


A) DEVICE-, DRAWING NUMBER: 17991	08.01.30		
B) ASSEMBLY CODE: SJZ-X	C) SCALE: 20 / 1		
D) DIE SIZE: 2.57 x 3.98 mm	E) DIE ATTACH PAD SIZE: 3.0x4.8 mm		
F) PACKAGE TYPE/BODY SIZE: TSSOP 20 LD	/ (4.4 mm)		
G) BONDPAD PITCH (MIN): 103 µm	H) BOND PAD SIZE (MIN): 85 μm		
I) WIRE SIZE:	J) WAFERTHICKNESS:		
K) CAVITY (UP OR DOWN): UP			
L) REMARKS:	QA – APPROVAL: REV.:		
	SHEET OF		



## 9 Package Drawings and Markings

Figure 14. 20-pin TSSOP Package



	Pad Name	Coordi	nates	
	Pad Name	х	У	
3 <b>V3</b> (	VDDD	291.4	2418	
	VDDA	407.85	2418	~
	TB0	717.2	2418	
	TB1	822.2	2418	
SCL SDA	PWM	2877.2	2418	
	CSn	3068.2	2418	
	CLK	3259.2	2418	
	DIO	3450.2	2418	
ADR -	I2C_A0	3641.2	2418	
	PDIO	3828	668.5	
	VSS	3526.75	52	

Pad Name	Coord	linates	
Pau Name	X	у	
VSS	3423.65	52	DGNZ
Mode_Index	3235.45	52	
COIL	3132.35	52	
DTEST2_B	720.6	52	-NC
DTEST1_A	383	52	- NC
MagDecrn	175.4	52	-NC
MagIncrn	52	1206.7	
TB2	52	1321.7	
TB3	52	1657.75	
VDDHall	52	1772.7	3 \ 3
VDD5V	52	2161	13,2